# **HRC0203B**

# Silicon Schottky Barrier Diode for Rectifying

# **HITACHI**

ADE-208-800(Z) Rev 0 June. 1999

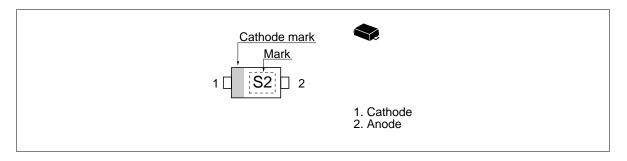
#### **Features**

- Low forward voltage drop and suitable for high effifiency rectifying.
- Ultra small Flat Package (UFP) is suitable for surface mount design.

### **Ordering Information**

Type No.	Laser Mark	Package Code
HRC0203B	S2	UFP

#### **Outline**





## HRC0203B

# Absolute Maximum Ratings ( $Ta = 25^{\circ}C$ )

Item	Symbol	Value	Unit
Repetitive peak reverse voltage	V <sub>RRM</sub> *1	30	V
Average rectified current	I <sub>o</sub> *1	200	mA
Non-Repetitive peak forward surge current	I <sub>FSM</sub> *2	3	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55Å`+125	°C

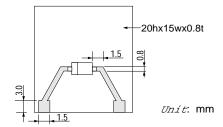
Note

- 1. See from Fig.3 to Fig.5
- 2. 10msec sine wave 1 pulse

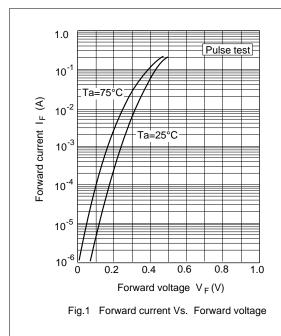
## **Electrical Characteristics** (Ta = $25^{\circ}$ C)

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	$V_{F}$	_	_	0.52	V	I <sub>F</sub> = 200 mA
Reverse current	$I_R$	_	_	10	μΑ	V <sub>R</sub> = 30V
Thermal resistance	R <sub>th(i-a)</sub>	_	500	_	°C/W	Polyimide board <sup>*1</sup>

### Note 1. Polyimide board



### **Main Characteristic**



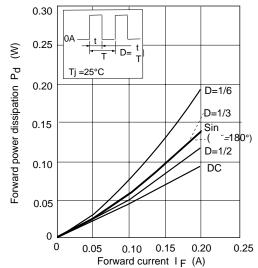


Fig.3 Forward power dissipation Vs. Forward current

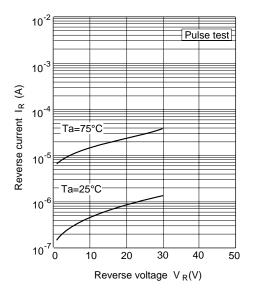


Fig.2 Reverse current Vs. Reverse voltage

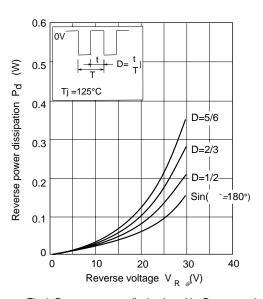
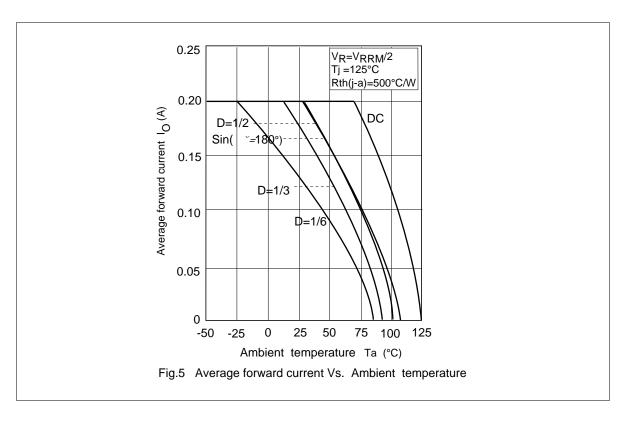


Fig.4 Reverse power dissipation Vs. Reverse voltage

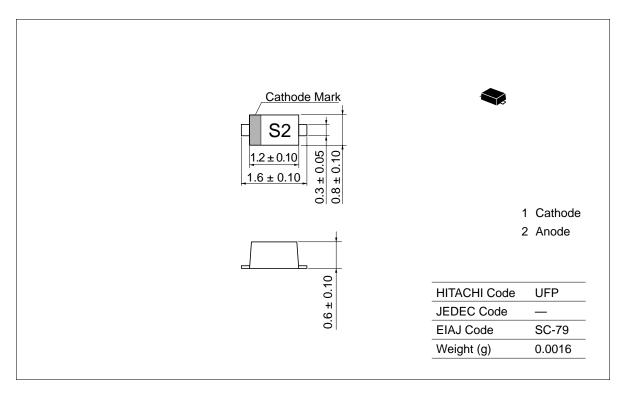
## HRC0203B

### **Main Characteristic**



# **Package Dimensions**

Unit: mm



#### **Cautions**

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#### Hitachi, Ltd.

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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#### For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Hitachi Europe GmbH Electronic components Group Dornacher Stra§e 3 D-85622 Feldkirchen, Munich Germany Tel: <49> (89) 9 9180-0

Fax: <49> (89) 9 29 30 00 Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom

Tel: <44> (1628) 585000 Fax: <44> (1628) 778322 Hitachi Asia Pte. Ltd. 16 Collyer Quay #20-00 Hitachi Tower Singapore 049318 Tel: 535-2100 Fax: 535-1533

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218

Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

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